ABSTRACT OF THE DISCLOSURE

A manufacturing process of a plurality of fluid jetting apparatuses in a print head adapted to an output unit. The process forms a heat driving part, a membrane and a nozzle part, respectively, and then adheres them sequentially. The fluid jetting apparatuses are completed as a wafer unit by forming the nozzle part using a spinning process. The manufacturing process of the nozzle part includes a first step of forming a nozzle plate on a substrate of a wafer by the spinning process; a second step of forming jetting fluid barriers on the nozzle plate by the spinning process; a third step of forming jetting fluid chambers in the jetting fluid barriers; a fourth step of forming nozzles in the nozzle plate; and a fifth step of separating the substrate from the nozzle plate. The fifth step is accomplished after the nozzle part and the membrane are adhered to each other. The third step is accomplished by a process of wet etching, and the fourth step is accomplished by a treating apparatus of a laser beam or by a process of reactive ion etching. Since the nozzle part is formed on the silicon wafer by means of the spinning process, it is capable of adhering to the membrane in a wafer type. Accordingly, the fluid jetting apparatuses are completed as the wafer type all at once. Furthermore, since the manufacturing time of the jetting fluid apparatuses is reduced, productivity is improved.